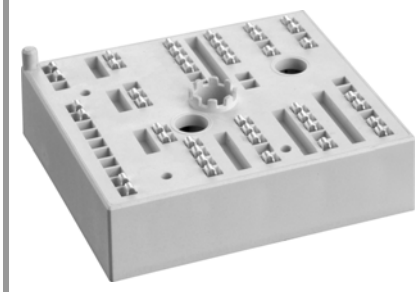
SKiiP 25AC12T4V1



MiniSKiiP® 2

SKiiP 25AC12T4V1

Features

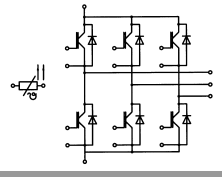
- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

Typical Applications*

- Inverter up to 26 kVA
- Typical motor power 15 kW

Remarks

- V_{CEsat} , V_F= chip level value
- Case temp. limited to T_C = 125°C max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. T_{op} = -40 … +150°C)



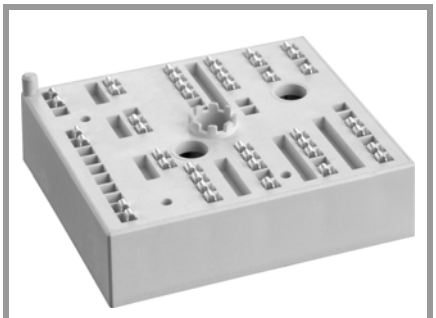
AC

Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V_{CES}	T_j = 25 °C		1200	V
I_C	λ_{paste}=0.8 W/(mK)	T_s = 25 °C	69	A
	T_j = 175 °C	T_s = 70 °C	56	A
I_C	λ_{paste}=2.5 W/(mK)	T_s = 25 °C	78	A
	T_j = 175 °C	T_s = 70 °C	64	A
I_{Cnom}			50	A
I_{CRM}	I_{CRM} = 3 x I_{Cnom}		150	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 800 V $V_{GE} \leq$ 15 V $V_{CES} \leq$ 1200 V	T_j = 150 °C	10	µs
T_j			-40 ... 175	°C
Inverse - Diode				
I_F	λ_{paste}=0.8 W/(mK)	T_s = 25 °C	60	A
	T_j = 175 °C	T_s = 70 °C	48	A
I_F	λ_{paste}=2.5 W/(mK)	T_s = 25 °C	68	A
	T_j = 175 °C	T_s = 70 °C	55	A
I_{Fnom}			50	A
I_{FRM}	I_{FRM} = 3 x I_{Fnom}		150	A
I_{FSM}	10 ms, sin 180°, T_j = 150 °C		270	A
T_j			-40 ... 175	°C
Module				
$I_{t(RMS)}$	$T_{terminal}$ = 80 °C, 20 A per spring		100	A
T_{stg}			-40 ... 125	°C
V_{isol}	AC sinus 50 Hz, t = 1 min		2500	V

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
$V_{CE(sat)}$	I_C = 50 A V_{GE} = 15 V chiplevel	T_j = 25 °C		1.85	2.10	V
		T_j = 150 °C		2.20	2.40	V
V_{CE0}	chiplevel	T_j = 25 °C		0.80	0.90	V
		T_j = 150 °C		0.70	0.80	V
r_{CE}	V_{GE} = 15 V chiplevel	T_j = 25 °C		21	24	mΩ
		T_j = 150 °C		30	32	mΩ
$V_{GE(th)}$	$V_{GE} = V_{CE}$, I_C = 2 mA		5	5.8	6.5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = 1200 V, T_j = 25 °C			0.1	0.3	mA
C_{ies}	V_{CE} = 25 V V_{GE} = 0 V	f = 1 MHz		2.77		nF
C_{oes}		f = 1 MHz		0.21		nF
C_{res}		f = 1 MHz		0.16		nF
Q_G	- 8 V...+ 15 V			283		nC
R_{Gint}	T_j = 25 °C			4.0		Ω
$t_{d(on)}$	V_{CC} = 600 V I_C = 50 A $R_{G\ on}$ = 12 Ω $R_{G\ off}$ = 12 Ω di/dt$_{on}$ = 1300 A/µs di/dt$_{off}$ = 640 A/µs	T_j = 150 °C		54		ns
t_r		T_j = 150 °C		36		ns
E_{on}		T_j = 150 °C		6		mJ
$t_{d(off)}$		T_j = 150 °C		340		ns
t_f		T_j = 150 °C		70		ns
E_{off}	V_{GE} = +15/-15 V	T_j = 150 °C		4.5		mJ
$R_{th(j-s)}$	per IGBT, λ_{paste}=0.8 W/(mK)			0.71		K/W
$R_{th(j-s)}$	per IGBT, λ_{paste}=2.5 W/(mK)			0.56		K/W



MiniSKiiP® 2

SKiiP 25AC12T4V1

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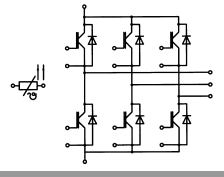
- product rel. results valid for $T_j \leq 150$ (recomm. T_{op} = -40 … +150°C)

Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
Inverse - Diode						
$V_F = V_{EC}$	I_F = 50 A V_{GE} = 0 V chiplevel	T_j = 25 °C		2.22	2.54	V
		T_j = 150 °C		2.18	2.50	V
V_{F0}	chiplevel	T_j = 25 °C		1.30	1.50	V
		T_j = 150 °C		0.90	1.10	V
r_F	chiplevel	T_j = 25 °C		18	21	mΩ
		T_j = 150 °C		26	28	mΩ
I_{RRM}	I_F = 50 A di/dt_{off} = 1400 A/µs V_{GE} = +15/-15 V V_{CC} = 600 V	T_j = 150 °C		51		A
Q_{rr}		T_j = 150 °C		8		µC
E_{rr}		T_j = 150 °C		3.2		mJ
$R_{th(j-s)}$	per Diode, λ_{paste}=0.8 W/(mK)			0.95		K/W
$R_{th(j-s)}$	per Diode, λ_{paste}=2.5 W/(mK)			0.78		K/W
Module						
L_{CE}				-		nH
M_s	to heat sink		2		2.5	Nm
w				55		g
Temperature Sensor						
R_{100}	T_r=100°C (R_{25}=1000Ω)			1670 ± 3%		Ω
R(T)	R(T)=1000Ω[1+A(T-25°C)+B(T-25°C)^2], A = 7.635*10^{-3} °C^{-1}, B = 1.731*10^{-5} °C^{-2}					



AC

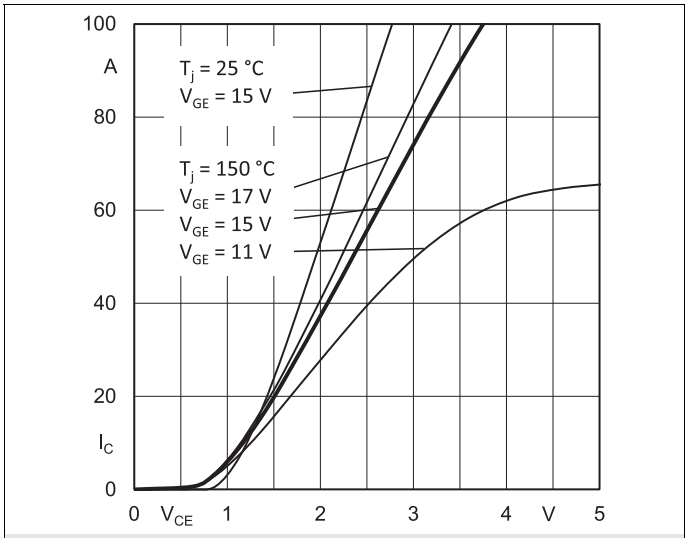


Fig. 1: Typ. output characteristic, inclusive $R_{CC'+EE'}$

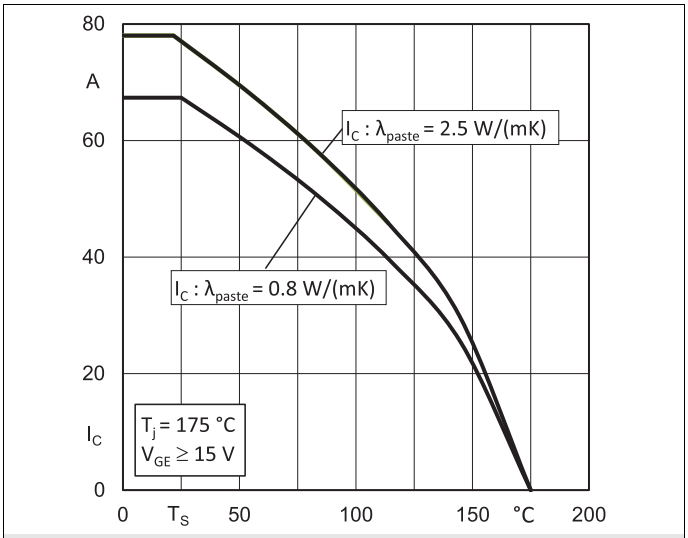


Fig. 2: Rated current vs. temperature $I_C = f(T_S)$

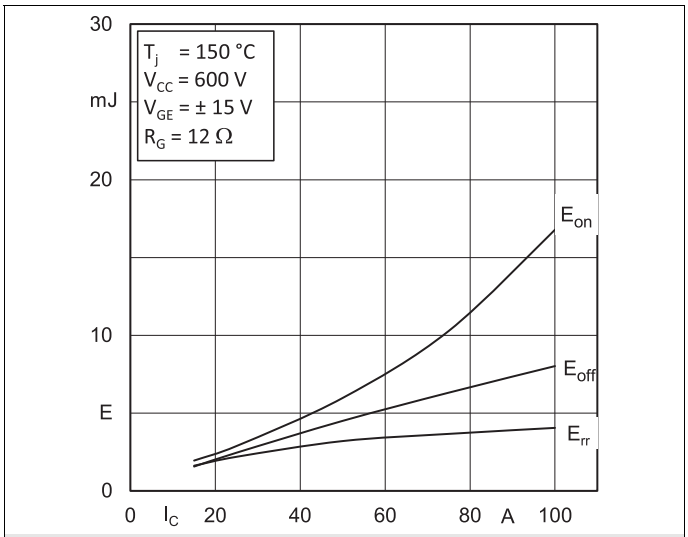


Fig. 3: Typ. turn-on /-off energy = f (I_C)

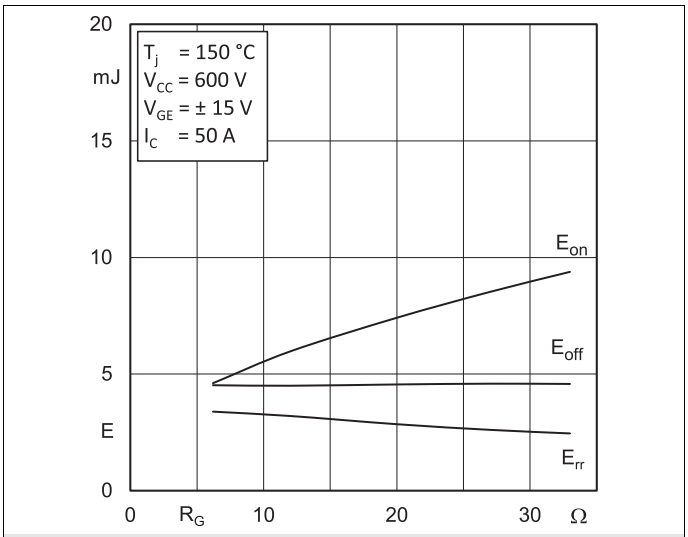


Fig. 4: Typ. turn-on /-off energy = f (R_G)

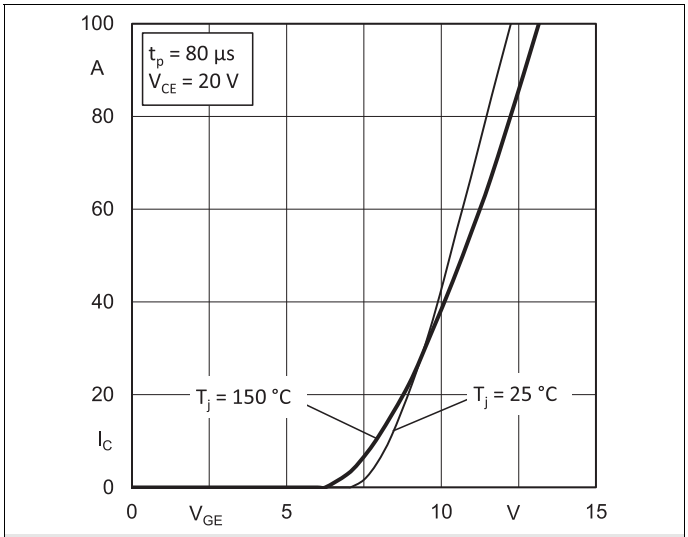


Fig. 5: Typ. transfer characteristic

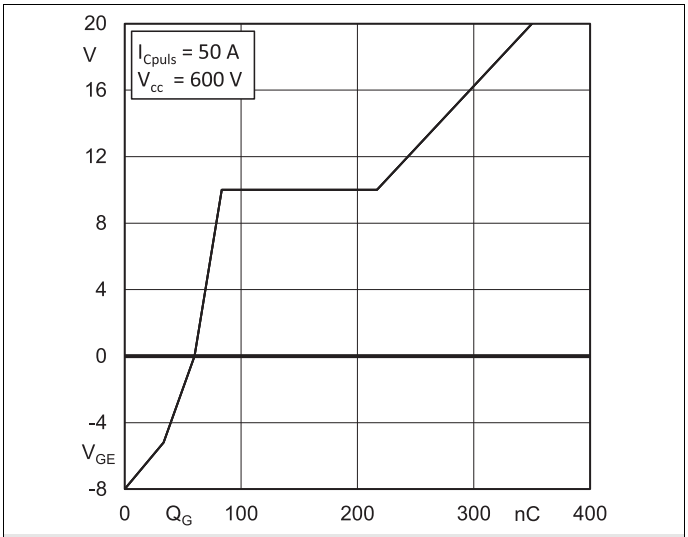


Fig. 6: Typ. gate charge characteristic

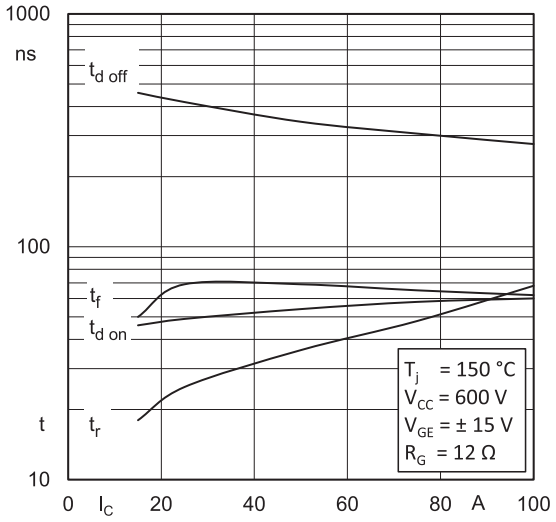


Fig. 7: Typ. switching times vs. I_C

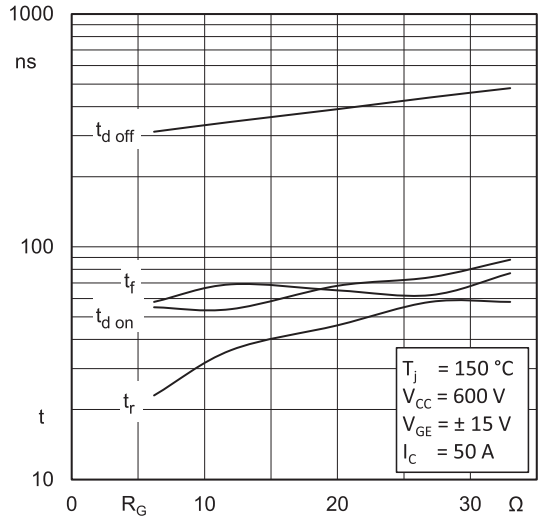


Fig. 8: Typ. switching times vs. gate resistor R_G

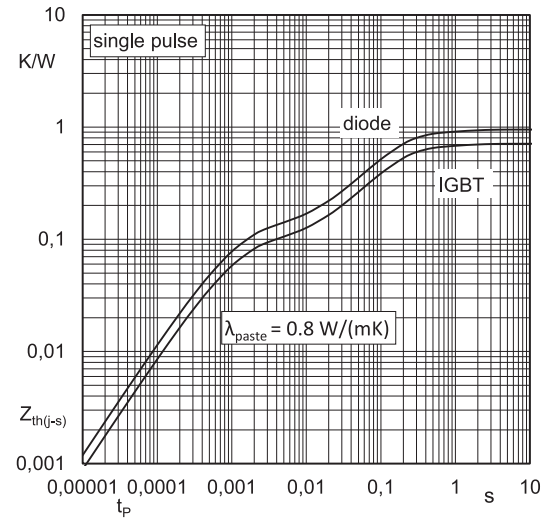


Fig. 9: Transient thermal impedance of IGBT and Diode

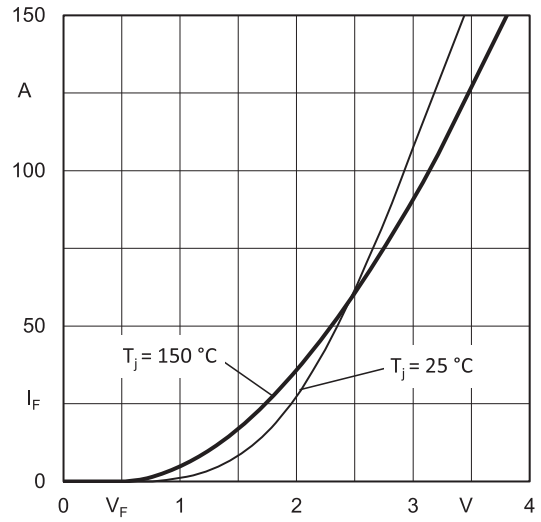


Fig. 10: CAL diode forward characteristic

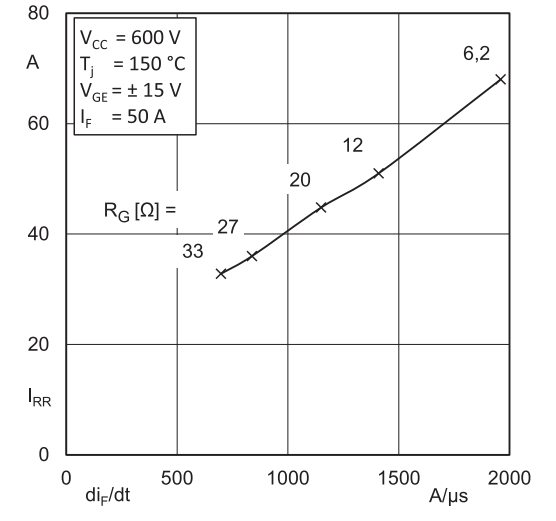


Fig. 11: Typ. CAL diode peak reverse recovery current

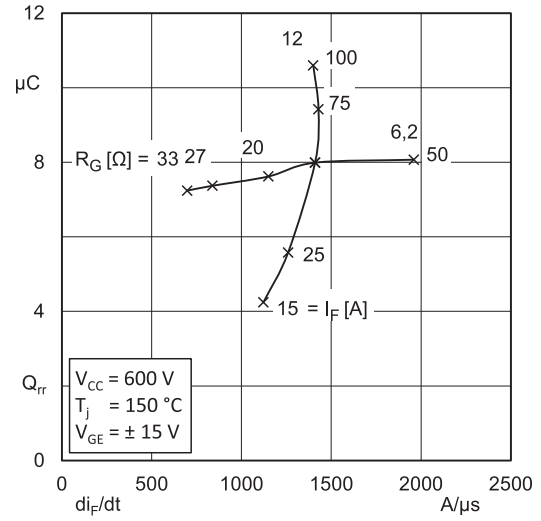
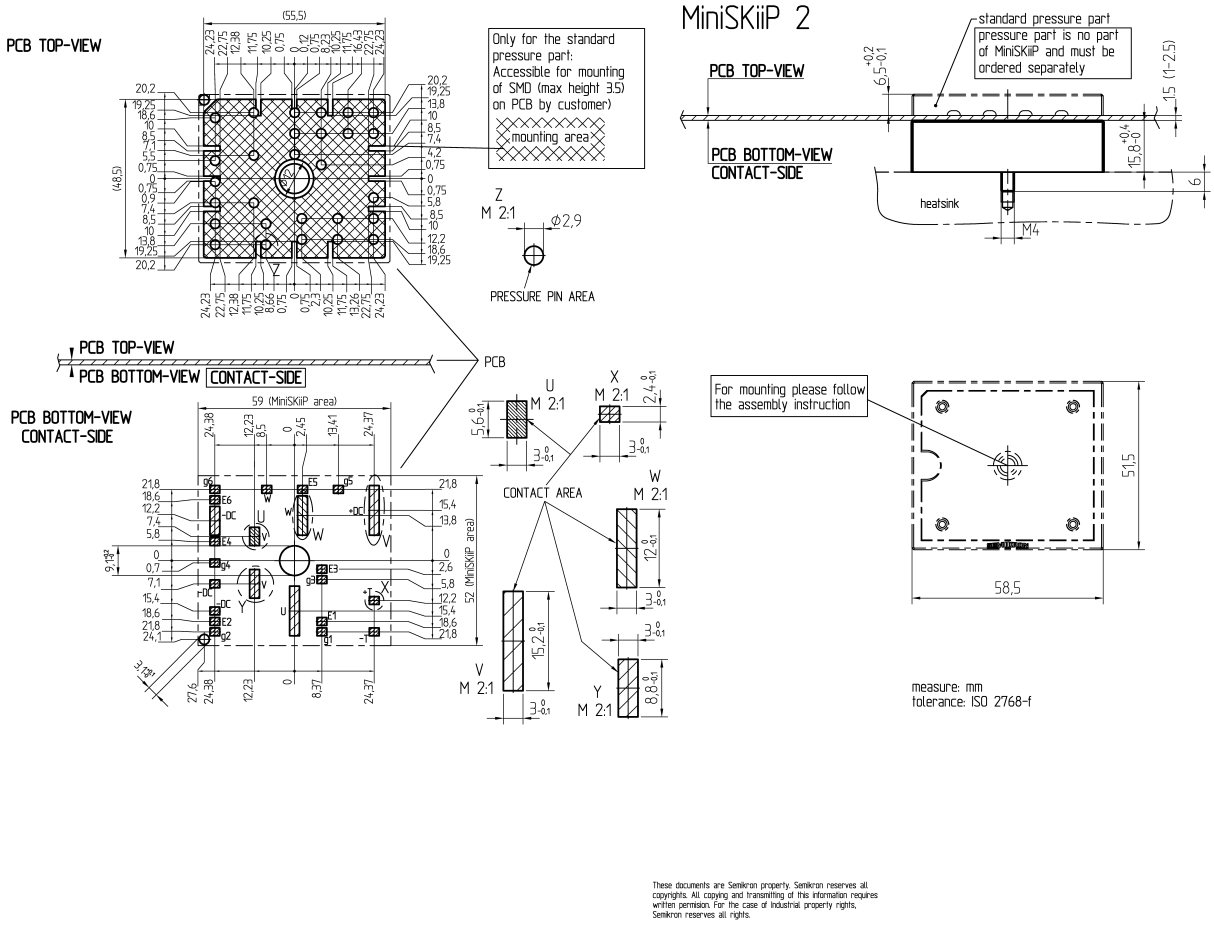
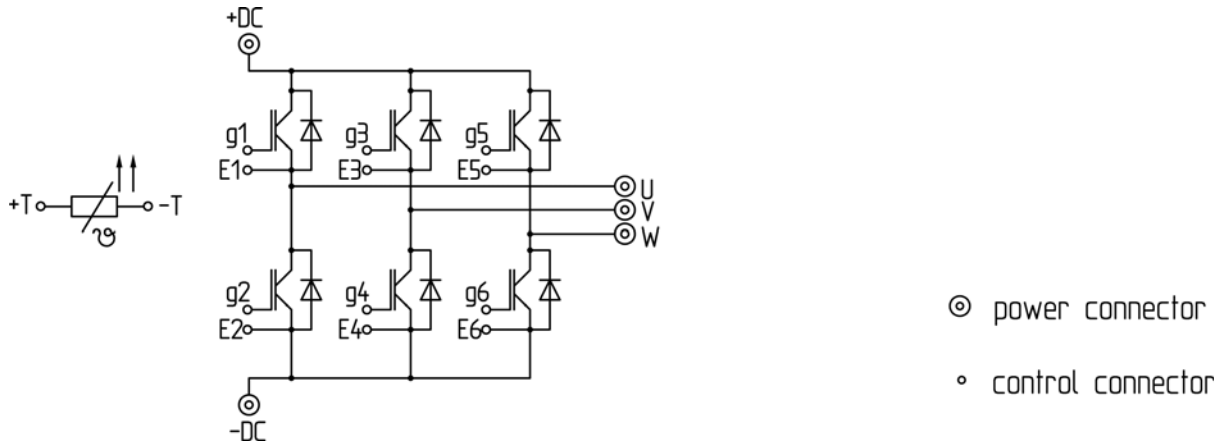


Fig. 12: Typ. CAL diode recovery charge



pinout, dimensions



pinout

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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